Express Mail Label No. EL 713 631 849 US **FORM PTO-1449 Docket Number (Optional) Application Number** 81839.0108 Not Assigned INFORMATION DISCLOSURE CITATION **Applicant** Takehito USHIKI; Hitoshi TSUNODA IN AN APPLICATION (Use several sheets if necessary) **Filing Date** Group Art Unit December 11, 2001 Not Assigned **U.S. PATENT DOCUMENTS EXAMINER DOCUMENT NUMBER** DATE **FILING DATE IF** NAME INITIAL **CLASS** SUBCLASS **APPROPRIATE** JUL_ 5,447,890 09/1995 Kato et al. 437 249 **FOREIGN PATENT DOCUMENTS DOCUMENT NUMBER** DATE COUNTRY **Translation** SUBCLASS **CLASS** YE\$ NO 91 :- EP 0782179 7/02/1997 **EPO** X # EP 0337556 10/18/1989 **EPO** X +WO 8912318 12/14/1989 PCT 4 EP 0764976 03/26/1997 **EPO** × Q.J.

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Abstract

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